



CyberOptics To Showcase High-Precision Inspection and Metrology Solutions at SEMI Technology Unites Global Summit

Minneapolis, Minnesota — January 29th, 2021 — [CyberOptics® Corporation](#) (NASDAQ: CYBE), a leading global developer and manufacturer of high-precision 3D sensing technology solutions, will feature the WX3000™ metrology and inspection system with MRS™ sensor technology, and high-precision sensors for semiconductor tool set-up and diagnostics at the Virtual [SEMI Technology Unites Global Summit](#) from February 15-19th.

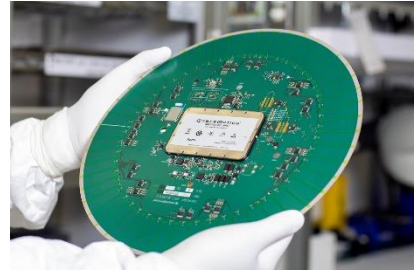
Tim Skunes, VP of R&D at CyberOptics, will share a related technical presentation 'Fast, 100% 3D Wafer Bump Metrology and Inspection to Improve Yields and 3D System Integration' on [February 16th](#). Advanced Packaging (AP) and wafer level packaging (WLP) continue to be among the most dynamic and rapidly evolving areas of semiconductor development and manufacturing. As the processes and features they create have become smaller and more complex, manufacturers face an increasing need for high-precision inspection and measurement to detect defects and improve process control. This need is amplified by the fact that these processes use expensive known good die, making the cost of failure extremely high.

The NanoResolution MRS sensor integrated into CyberOptics' [WX3000™](#) system provides sub-micrometer accuracy on features as small as 25µm. While retaining its ability to reject spurious multiple reflections, it adds the ability to capture and analyze specular reflections from shiny surfaces of solder balls, bumps and pillars, allowing highly accurate inspection and 3D metrology of these critical packaging features. Complete 100% 3D/2D inspection and bump metrology can be accomplished vs. time-consuming alternative methods that require separate scans for 3D and 2D, or a sampling only approach. With data processing speeds in excess of 75 million 3D points per second, it delivers production-worthy throughput greater than 25 wafers (300mm) per hour, at speeds 2-3X faster.



“Whether it’s for the back-end or mid-end of the semiconductor fab, our proprietary sensors and systems deliver significant benefits to customers in terms of improved yields, processes and productivity,” said Dr. Subodh Kulkarni, President and CEO, CyberOptics, “Compared to other solutions, our technology saves our customers significant time and expense.”

The company will also digitally demonstrate high-precision sensors that process and equipment engineers use in the front-end of the fab to speed equipment qualification, shorten equipment maintenance cycles, lower equipment expenses and optimize preventative maintenance plans. The WaferSense® Auto Resistance Sensor™ ([ARS](#)) enables real-time resistance measurements of plating cell contacts in semiconductor Electrochemical Deposition (ECD) applications, and the In-Line Particle Sensor™ ([IPS](#)) detects, monitors and enables troubleshooting of particles down to 0.1 μm in gas and vacuum lines in any areas of the fab 24/7.



The Technology Unites Global Summit brings together the global microelectronics supply chain, manufacturers and end users for a digital experience featuring industry thought leaders and high-value technical content from around the world. CyberOptics is a platinum sponsor.

For more information, visit www.cyberoptics.com.

About CyberOptics

CyberOptics Corporation (www.cyberoptics.com) is a leading global developer and manufacturer of high-precision 3D sensing technology solutions. CyberOptics' sensors are used for inspection and metrology in the SMT and semiconductor markets to significantly improve yields and productivity. By leveraging its leading edge technologies, the Company has strategically established itself as a global leader in high precision 3D sensors, allowing CyberOptics to further increase its penetration of key vertical markets. Headquartered in Minneapolis, Minnesota, CyberOptics conducts worldwide operations through its facilities in North America, Asia and Europe.

Statements regarding the Company's anticipated performance are forward-looking and therefore involve risks and uncertainties, including but not limited to: a possible world-wide recession or depression resulting from the economic consequences of the COVID-19 pandemic; the negative effect on our revenue and operating results of the COVID-19 crisis on our customers and suppliers and the global supply chain; market conditions in the global SMT and semiconductor capital equipment industries; trade relations between the United States and China and other countries; the timing of orders and shipments of our products, particularly our 3D MRS™ SQ3000 Multi-Function systems™ and MX systems for memory module inspection; increasing price competition and price pressure on our product sales, particularly our SMT systems; the level of orders from our OEM customers; the availability of parts required to meet customer orders; unanticipated product development challenges; the effect of world events on our sales, the majority of which are from foreign customers; rapid changes in technology in the electronics and semiconductor markets; product introductions and pricing by our competitors; the success of our 3D technology initiatives; the market acceptance of our SQ3000 MultiFunction™ inspection and measurement systems and products for semiconductor advanced packaging inspection and metrology; costly and time consuming litigation with third parties related to intellectual property infringement; the negative impact on our customers and suppliers due to past and future terrorist threats and attacks and any acts of war; the impact of the MX3000™ orders on our consolidated gross margin percentage in any future period; risks related to cancellation or renegotiation of orders we have received; and other factors set forth in the Company's filings with the Securities and Exchange Commission.

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